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#### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

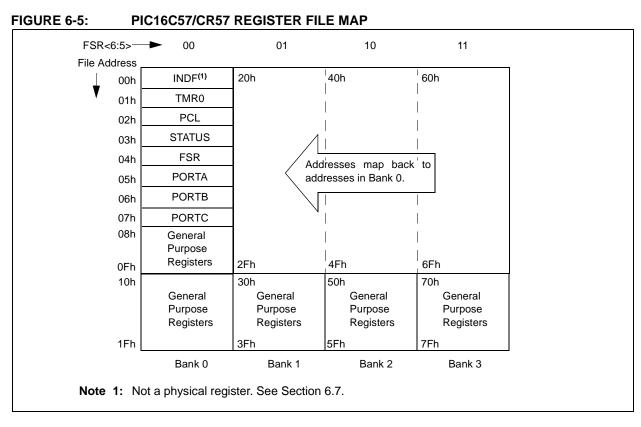
#### Details

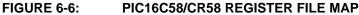
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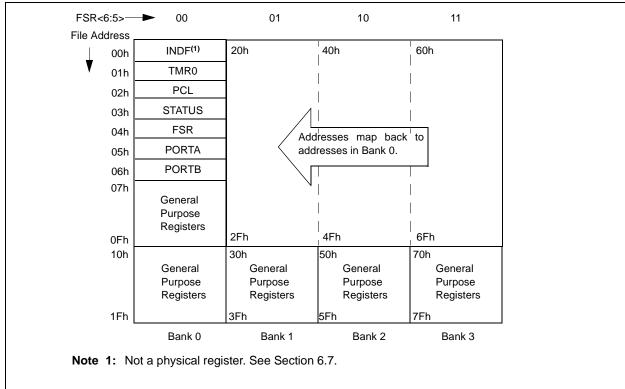
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	73 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	<u>.</u>
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc58bt-04-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong







#### CONFIGURATION WORD FOR PIC16C54/C55/C56/C57 **REGISTER 9-2:**

							İ	СР	WDTE	FOSC1	FOSC0
		_	_	_				CP	WDIE	FUSCI	
bit 11											bit 0
bit 11-4:	Unimple	mented	Read as '	0'							
bit 3:	CP: Cod	e protecti	on bit.								
		e protecti									
	0 = Code	e protectio	on on								
bit 2:	WDTE: \	Vatchdog	timer ena	ble bit							
	1 = WDT	enabled									
	0 = WDT	disabled									
bit 1-0:	FOSC1:I	FOSC0: (	Oscillator s	election b	oits <sup>(2)</sup>						
	00 = LF	oscillato	or								
	01 = X	T oscillato	or								
		S oscillato									
	11 = R	C oscillate	or								
Note 1.	Refer to t	ha PIC16	C5X Prog	rammina	Specificat	ions (Liter	atura Num	her DS3	190) to d	otormino l	now to
			iration wor	0	opeemear				, 100) to u		1011 10
2:		•	orts XT, R		oscillator	onlv.					
						- 1					
Legend:											

Legend:				
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'		
-n = Value at POR	1 = bit is set	0 = bit is cleared	x = bit is unknown	

# 10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1:	OPCODE FIELD
	DESCRIPTIONS

	DESCRIPTIONS
Field	Description
f	Register file address (0x00 to 0x1F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with $x = 0$ . It is the recommended form of use for com-
	patibility with all Microchip software tools.
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
WDT	Watchdog Timer Counter
TO	Time-out bit
PD	Power-down bit
dest	Destination, either the W register or the specified register file location
[ ]	Options
( )	Contents
$\rightarrow$	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1  $\mu$ s. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2  $\mu$ s.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

# FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS

Byte-oriented file regis	ter o	perations						
<u>11 6</u>	5	4 0						
OPCODE	d	f (FILE #)						
d = 0 for destination d = 1 for destination f = 5-bit file register	on f							
Bit-oriented file registe	r ope	erations						
11 8	7	5 4 0						
OPCODE	b (Bl	IT #) f (FILE #)						
Literal and control ope	<ul> <li>b = 3-bit bit address</li> <li>f = 5-bit file register address</li> <li>Literal and control operations (except GOTO)</li> </ul>							
11	8	7 0						
OPCODE		k (literal)						
k = 8-bit immedia	te va	alue						
Literal and control ope	eratio	ons - GOTO instruction						
11	9	8 0						
OPCODE		k (literal)						
k = 9-bit immedia	te va	alue						

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# 11.0 DEVELOPMENT SUPPORT

The PIC<sup>®</sup> microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB<sup>®</sup> IDE Software
- Assemblers/Compilers/Linkers
  - MPASM<sup>™</sup> Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/
  - MPLIB<sup>™</sup> Object Librarian
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - ICEPIC<sup>™</sup> In-Circuit Emulator
- In-Circuit Debugger
- MPLAB ICD
- Device Programmers
  - PRO MATE<sup>®</sup> II Universal Device Programmer
- PICSTART<sup>®</sup> Plus Entry-Level Development Programmer
- Low Cost Demonstration Boards
  - PICDEM<sup>™</sup>1 Demonstration Board
  - PICDEM 2 Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 17 Demonstration Board
  - KEELOQ<sup>®</sup> Demonstration Board

#### 11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. The MPLAB IDE is a Windows<sup>®</sup>-based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor
- A project manager
- Customizable toolbar and key mapping
- A status bar
- On-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC MCU emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files
  - absolute listing file
  - machine code

The ability to use MPLAB IDE with multiple debugging tools allows users to easily switch from the cost-effective simulator to a full-featured emulator with minimal retraining.

## 11.2 MPASM Assembler

The MPASM assembler is a full-featured universal macro assembler for all PIC MCUs.

The MPASM assembler has a command line interface and a Windows shell. It can be used as a stand-alone application on a Windows 3.x or greater system, or it can be used through MPLAB IDE. The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel<sup>®</sup> standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file that contains source lines and generated machine code, and a COD file for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects.
- User-defined macros to streamline assembly code.
- Conditional assembly for multi-purpose source files.
- Directives that allow complete control over the assembly process.

### 11.3 MPLAB C17 and MPLAB C18 C Compilers

The MPLAB C17 and MPLAB C18 Code Development Systems are complete ANSI 'C' compilers for Microchip's PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

	Standard Operating Conditions (unless otherwise specified)								
AC Chara	cteristics	Operating Temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial							
				TA ≤ +125					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
1	Tosc	External CLKIN Period <sup>(1)</sup>	250	—	_	ns	XT OSC mode		
			100	—	—	ns	10 MHz mode		
			50	—	—	ns	HS osc mode (Comm/Ind)		
			62.5	—	—	ns	HS osc mode (Ext)		
			25		_	μS	LP OSC mode		
		Oscillator Period <sup>(1)</sup>	250	—	—	ns	RC OSC mode		
			250	—	10,000	ns	XT OSC mode		
			100	—	250	ns	10 MHz mode		
			50	—	250	ns	HS OSC mode (Comm/Ind)		
			62.5	—	250	ns	HS osc mode (Ext)		
			25	—	_	μS	LP OSC mode		
2	Тсу	Instruction Cycle Time <sup>(2)</sup>	—	4/Fosc		—			
3	TosL,	Clock in (OSC1) Low or High	85*	—	—	ns	XT oscillator		
	TosH	Time	20*	—	—	ns	HS oscillator		
			2.0*	—		μS	LP oscillator		
4	TosR,	Clock in (OSC1) Rise or Fall	—	—	25*	ns	XT oscillator		
	TosF	Time	—	—	25*	ns	HS oscillator		
			—	—	50*	ns	LP oscillator		

#### TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

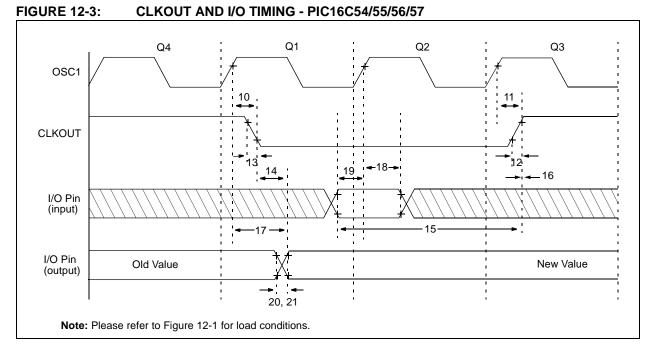
\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TCY) equals four times the input oscillator time base period.

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#### TABLE 12-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Char	acteristics	$\begin{array}{llllllllllllllllllllllllllllllllllll$	$\begin{array}{llllllllllllllllllllllllllllllllllll$						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units			
10	TosH2ckL	OSC1↑ to CLKOUT↓ <sup>(1)</sup>	_	15	30**	ns			
11	TosH2ckH	OSC1↑ to CLKOUT↑ <sup>(1)</sup>	_	15	30**	ns			
12	TckR	CLKOUT rise time <sup>(1)</sup>		5.0	15**	ns			
13	TckF	CLKOUT fall time <sup>(1)</sup>	—	5.0	15**	ns			
14	TckL2ioV	CLKOUT↓ to Port out valid <sup>(1)</sup>			40**	ns			
15	TioV2ckH	Port in valid before CLKOUT <sup>(1)</sup>	0.25 TCY+30*	_	_	ns			
16	TckH2iol	Port in hold after CLKOUT <sup>(1)</sup>	0*	_	_	ns			
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid <sup>(2)</sup>	_		100*	ns			
18	TosH2iol	OSC1 <sup>↑</sup> (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—		ns			
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns			
20	TioR	Port output rise time <sup>(2)</sup>	—	10	25**	ns			
21	TioF	Port output fall time <sup>(2)</sup>	—	10	25**	ns			

\* These parameters are characterized but not tested.

\*\* These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

**Note 1:** Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 12-1 for load conditions.

#### 13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 PIC16LCR54A-04I (Commercial, Industrial)				$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
PIC16CR54A-04, 10, 20 PIC16CR54A-04I, 10I, 20I (Commercial, Industrial)			$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions		
	Vdd	Supply Voltage							
D001		PIC16LCR54A	2.0		6.25	V			
D001 D001A		PIC16CR54A	2.5 4.5	_	6.25 5.5	V V	RC and XT modes HS mode		
D002	Vdr	RAM Data Retention Voltage <sup>(1)</sup>	_	1.5*	_	V	Device in SLEEP mode		
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset		
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	—	V/ms	See Section 5.1 for details on Power-on Reset		
	Idd	Supply Current <sup>(2)</sup>							
D005		PICLCR54A	_	10	20 70	μΑ μΑ	Fosc = 32 kHz, VDD = 2.0V Fosc = 32 kHz, VDD = 6.0V		
D005A		PIC16CR54A		2.0 0.8 90	3.6 1.8 350	mA mA μA	<b>RC<sup>(3)</sup> and XT modes:</b> Fosc = 4.0 MHz, VDD = 6.0V Fosc = 4.0 MHz, VDD = 3.0V Fosc = 200 kHz, VDD = 2.5V <b>HS mode:</b>		
				4.8 9.0	10 20	mA mA	Fosc = 10 MHz, VDD = 5.5V Fosc = 20 MHz, VDD = 5.5V		

Legend: Rows with standard voltage device data only are shaded for improved readability.

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
  - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
  - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .

#### 13.1 DC Characteristics: PIC16CR54A-04, 10, 20, PIC16LCR54A-04 (Commercial) PIC16CR54A-04I, 10I, 20I, PIC16LCR54A-04I (Industrial)

PIC16LCR54A-04 PIC16LCR54A-04I (Commercial, Industrial)				$\begin{array}{ l l l l l l l l l l l l l l l l l l l$						
PIC16CR	C16CR54A-04, 10, 20 C16CR54A-04I, 10I, 20I Commercial, Industrial)			$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions			
	IPD	Power-down Current <sup>(2)</sup>								
D006		PIC16LCR54A-Commercial		1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled			
D006A		PIC16CR54A-Commercial		1.0 2.0 3.0 5.0	6.0 8.0* 15 25	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled			
D007		PIC16LCR54A-Industrial		1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled			
D007A		PIC16CR54A-Industrial		1.0 2.0 3.0 3.0 5.0	8.0 10* 20* 18 45	μΑ μΑ μΑ μΑ	VDD = 2.5V, WDT disabled VDD = 4.0V, WDT disabled VDD = 4.0V, WDT enabled VDD = 6.0V, WDT disabled VDD = 6.0V, WDT enabled			

Legend: Rows with standard voltage device data only are shaded for improved readability.

- \* These parameters are characterized but not tested.
- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .

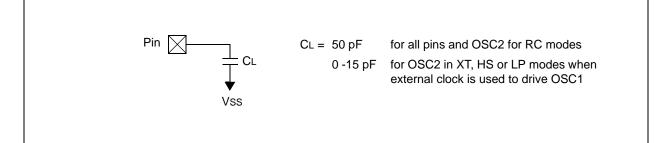
# 13.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS

2. Tp	ρS	
Т		
F	Frequency	T Time
Lowe	ercase letters (pp) and their meanings:	
рр		
2	to	mc MCLR
ck	CLKOUT	osc oscillator
су	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer
Uppe	ercase letters and their meanings:	
S		
F	Fall	P Period
н	High	R Rise
T	Invalid (Hi-impedance)	V Valid
L	Low	Z Hi-impedance

#### FIGURE 13-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16CR54A



AC Char	acteristics	Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
1	Tosc	External CLKIN Period <sup>(1)</sup>	250	_	_	ns	XT osc mode	
			250	—	—	ns	HS osc mode (04)	
			100	—		ns	HS osc mode (10)	
			50	—		ns	HS osc mode (20)	
			5.0	_	—	μS	LP OSC mode	
		Oscillator Period <sup>(1)</sup>	250		_	ns	RC OSC mode	
			250	—	10,000	ns	XT OSC mode	
			250	—	250	ns	HS OSC mode (04)	
			100	—	250	ns	HS osc mode (10)	
			50	—	250	ns	HS osc mode (20)	
			5.0	_	200	μS	LP OSC mode	
2	Тсу	Instruction Cycle Time <sup>(2)</sup>	—	4/Fosc		_		
3	TosL, TosH	Clock in (OSC1) Low or High	50*		_	ns	XT oscillator	
		Time	20*	—	—	ns	HS oscillator	
			2.0*	_	—	μS	LP oscillator	
4	TosR, TosF	Clock in (OSC1) Rise or Fall	_	—	25*	ns	XT oscillator	
		Time	—	—	25*	ns	HS oscillator	
			—	—	50*	ns	LP oscillator	

TABLE 13-1:	EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A
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These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

when an external clock input is used, the "max" cycle time limit is "Du" (no clock) for all device

2: Instruction cycle period (TcY) equals four times the input oscillator time base period.



#### FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16CR54A

#### TABLE 13-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16CR54A

AC Chara	cteristics	$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \\ \end{array} $						
Param No.	Symbol	Characteristic Min Typ† Max Units Conditions						
30	TmcL	MCLR Pulse Width (low)	1.0*			μS	VDD = 5.0V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7.0*	18*	40*	ms	VDD = 5.0V (Comm)	
32	Tdrt	Device Reset Timer Period	7.0*	18*	30*	ms	VDD = 5.0V (Comm)	
34	Tioz	I/O Hi-impedance from MCLR Low			1.0*	μS		

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 15-1:	EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A
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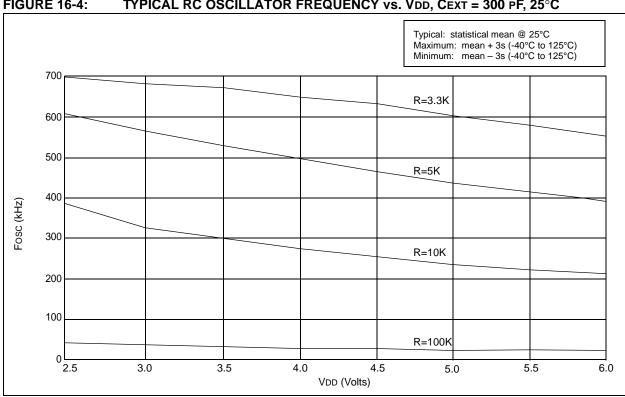
$\begin{array}{c} \mbox{Standard Operating Conditions (unless otherwise specified)}\\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial}\\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial}\\ -20^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} - PIC16LV54A-02I\\ -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for extended} \end{array}$							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
1	Tosc	External CLKIN Period <sup>(1)</sup>	250			ns	XT OSC mode
			500	—		ns	XT osc mode (PIC16LV54A)
			250	—		ns	HS osc mode (04)
			100	—		ns	HS osc mode (10)
			50	—		ns	HS osc mode (20)
			5.0	—		μs	LP OSC mode
		Oscillator Period <sup>(1)</sup>	250	—		ns	RC osc mode
			500	—		ns	RC osc mode (PIC16LV54A)
			250	—	10,000	ns	XT OSC mode
			500	—		ns	XT osc mode (PIC16LV54A)
			250	—	250	ns	HS osc mode (04)
			100	—	250	ns	HS osc mode (10)
			50	—	250	ns	HS osc mode (20)
			5.0		200	μs	LP OSC mode
2	Тсу	Instruction Cycle Time <sup>(2)</sup>		4/Fosc	—	—	
3	TosL, TosH	Clock in (OSC1) Low or	85*		_	ns	XT oscillator
		High Time	20*	—	—	ns	HS oscillator
			2.0*	_	—	μS	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or	_	_	25*	ns	XT oscillator
		Fall Time	—		25*	ns	HS oscillator
			_		50*	ns	LP oscillator

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

**2:** Instruction cycle period (TCY) equals four times the input oscillator time base period.



#### **FIGURE 16-4:** TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 300 PF, 25°C

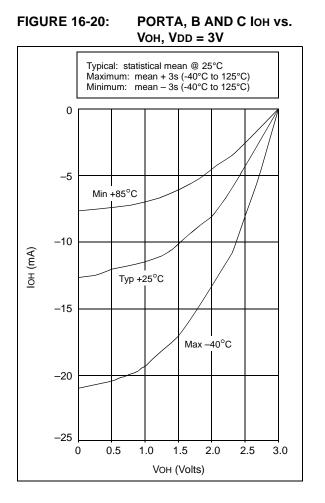
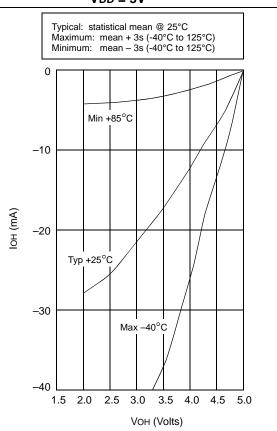


FIGURE 16-21: PORTA, B AND C IOH vs. VOH, VDD = 5V



#### 17.1 DC Characteristics:PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)			Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrialStandard Operating Conditions (unless otherwise specified)							
PIC16C5X PIC16CR5X (Commercial, Industrial)				ting Terr	-		$0^{\circ}C \le TA \le +70^{\circ}C$ for commercial -40°C $\le TA \le +85^{\circ}C$ for industrial			
Param No.	Symbol	Characteristic/Device	Min	Min Typ† Max Units		Units	Conditions			
	Vdd	Supply Voltage								
D001		PIC16LC5X	2.5 2.7 2.5		5.5 5.5 5.5	V V V	$\begin{array}{l} -40^{\circ}C \leq TA \leq +\ 85^{\circ}C,\ 16LCR5X \\ -40^{\circ}C \leq TA \leq 0^{\circ}C,\ 16LC5X \\ 0^{\circ}C \leq TA \leq +\ 85^{\circ}C\ 16LC5X \end{array}$			
D001A		PIC16C5X	3.0 4.5	_	5.5 5.5	V V	RC, XT, LP and HS mode from 0 - 10 MHz from 10 - 20 MHz			
D002	Vdr	RAM Data Retention Volt- age <sup>(1)</sup>	—	1.5*	—	V	Device in SLEEP mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset			

Legend: Rows with standard voltage device data only are shaded for improved readability.

\* These parameters are characterized but not tested.

- † Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
  - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k $\Omega$ .



FIGURE 18-4: TYPICAL RC OSCILLATOR FREQUENCY vs. VDD, CEXT = 300 PF, 25°C





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NOTES:



#### TABLE 20-1: INPUT CAPACITANCE

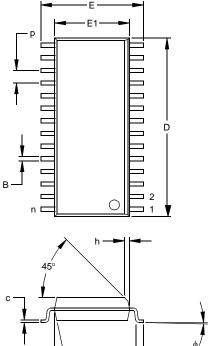
Pin	Typical Capacitance (pF)				
FIII	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
тоскі	3.2	2.8			

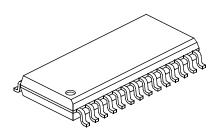
All capacitance values are typical at  $25^{\circ}$ C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

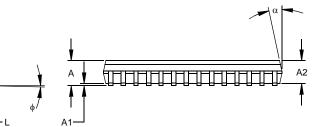


#### 28-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

For the most current package drawings, please see the Microchip Packaging Specification located Note: at http://www.microchip.com/packaging







	Units		INCHES*		MILLIMETERS			
Dimensi	MIN	IN NOM MAX		MIN NOM		MAX		
Number of Pins	n		28			28		
Pitch	р		.050			1.27		
Overall Height	Α	.093	.099	.104	2.36	2.50	2.64	
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39	
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30	
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67	
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59	
Overall Length	D	.695	.704	.712	17.65	17.87	18.08	
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74	
Foot Length	L	.016	.033	.050	0.41	0.84	1.27	
Foot Angle Top	ø	0	4	8	0	4	8	
Lead Thickness	С	.009	.011	.013	0.23	0.28	0.33	
Lead Width	В	.014	.017	.020	0.36	0.42	0.51	
Mold Draft Angle Top	α	0	12	15	0	12	15	
Mold Draft Angle Bottom	β	0	12	15	0	12	15	

\* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-013 Drawing No. C04-052

NOTES: